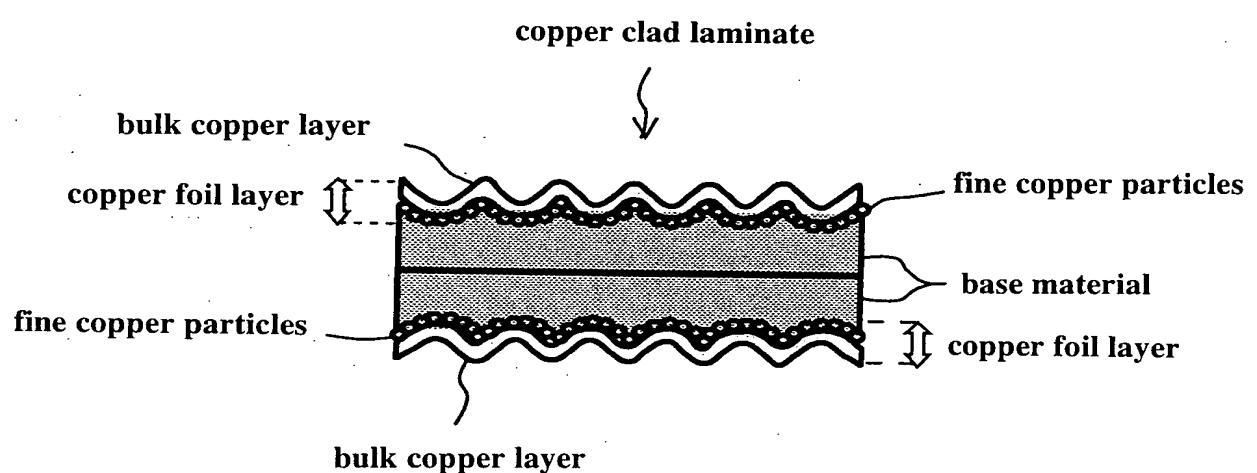
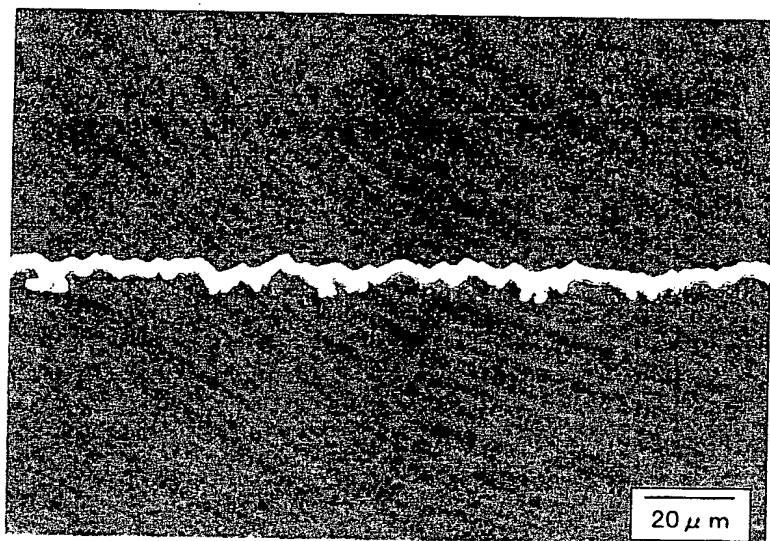


**FIG. 1**



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**FIG. 2**



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0.9355232 - 0.5450

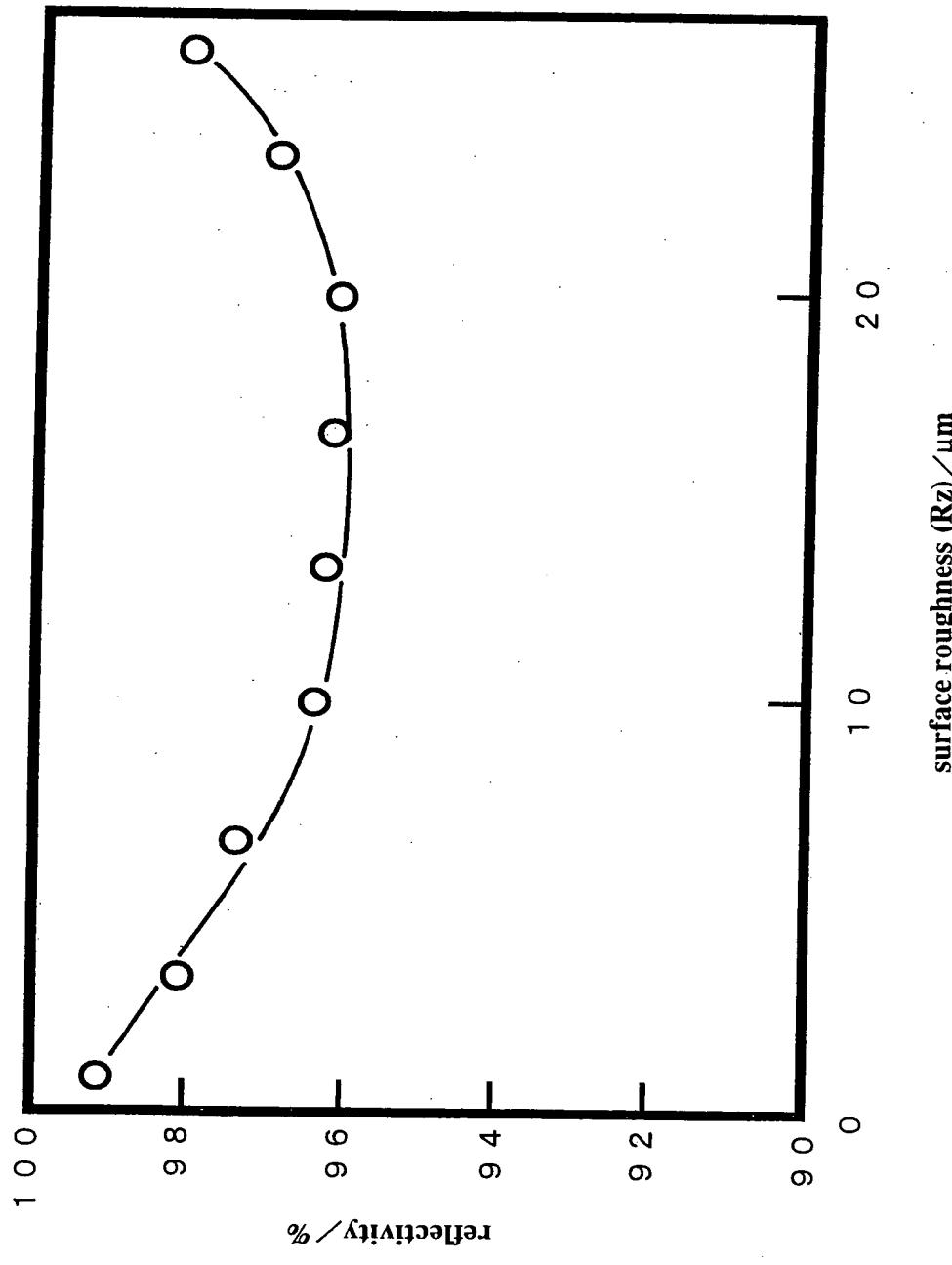
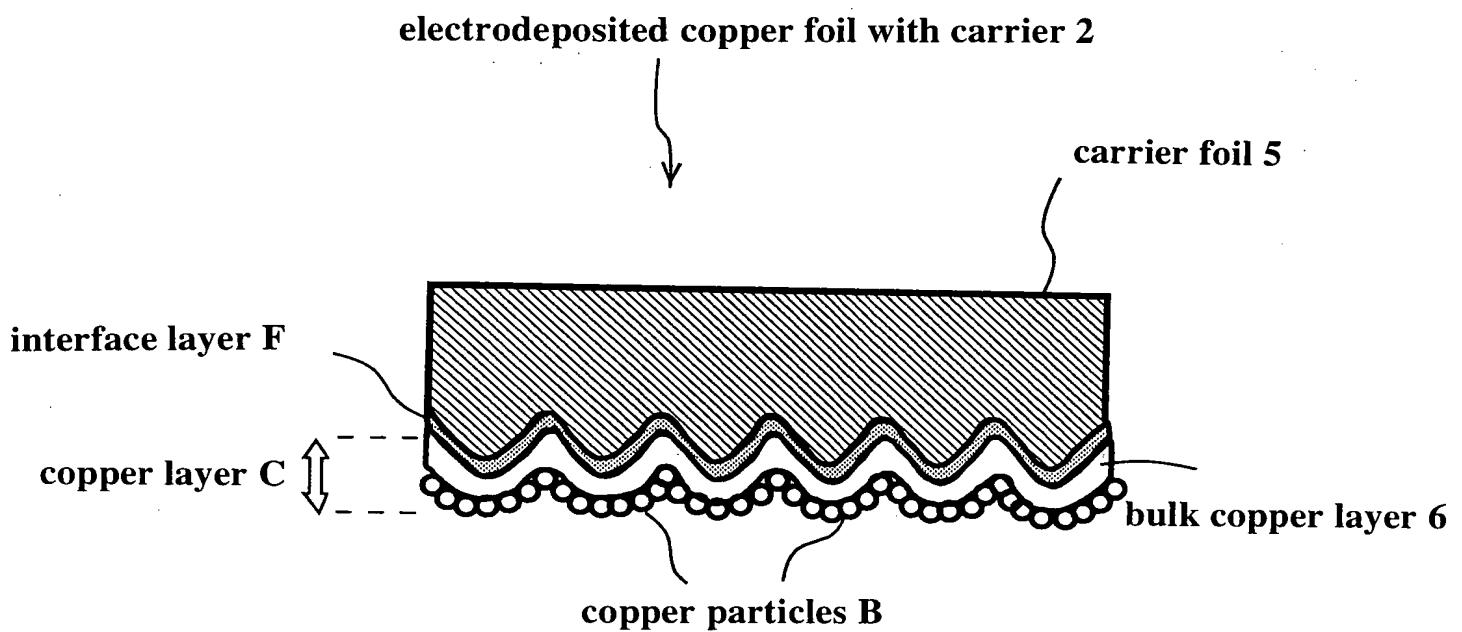


FIG. 3

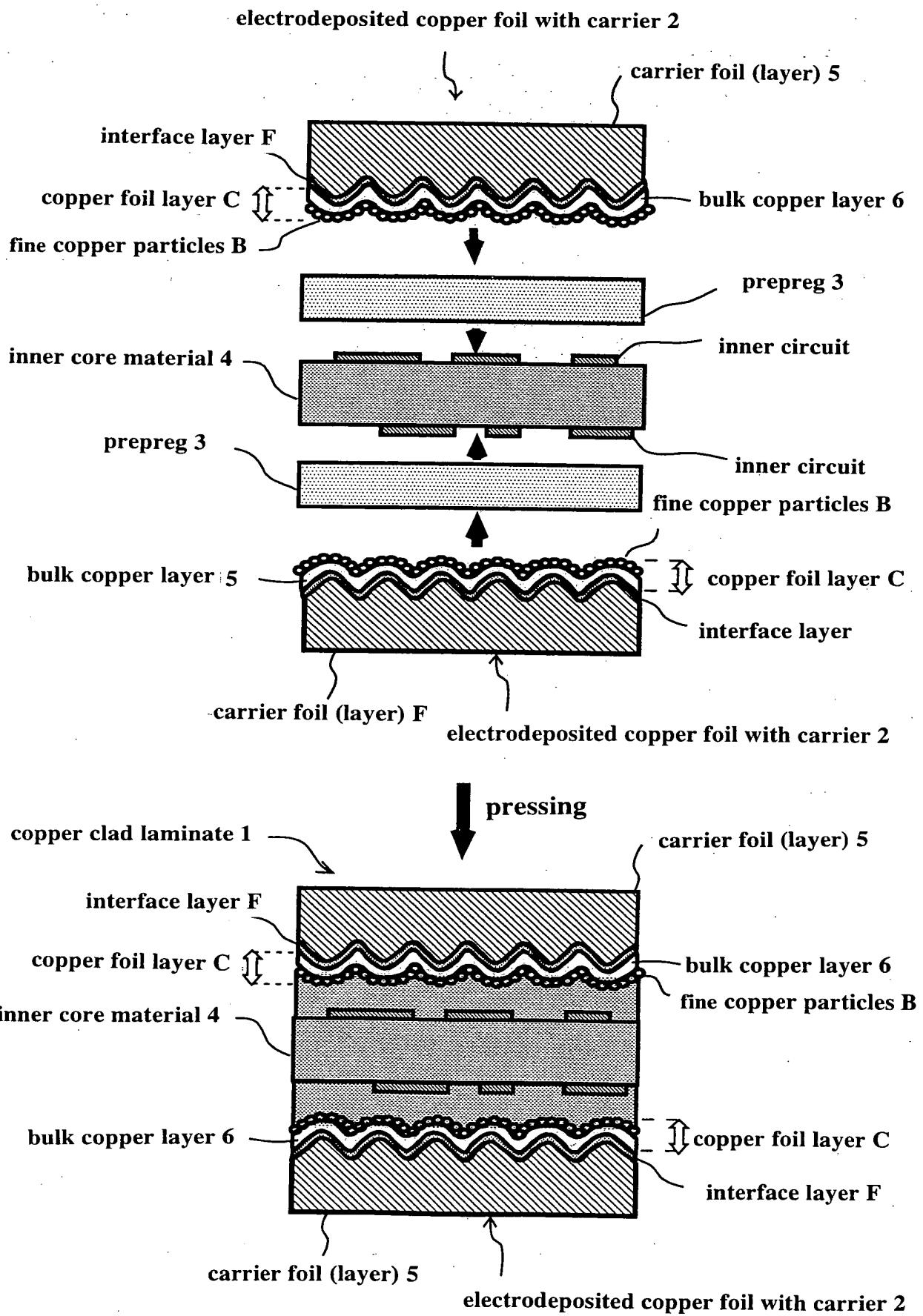
**FIG. 4**



0 9 6 5 5 3 8 2 - 0 5 1 5 0 3

# FIG. 5

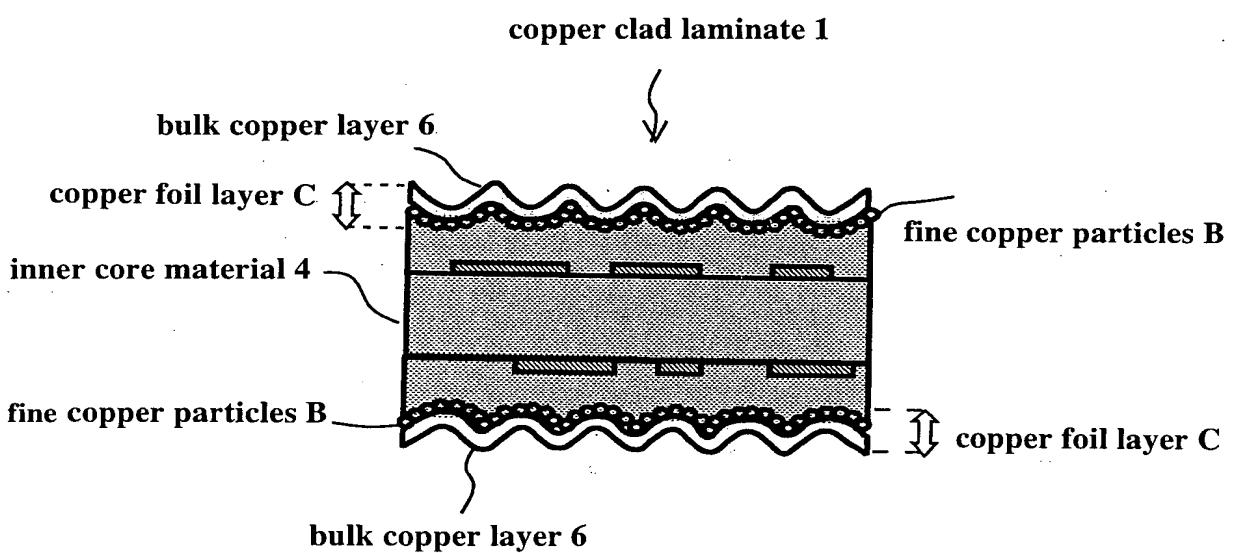
## (a) Manufacturing of copper clad laminate



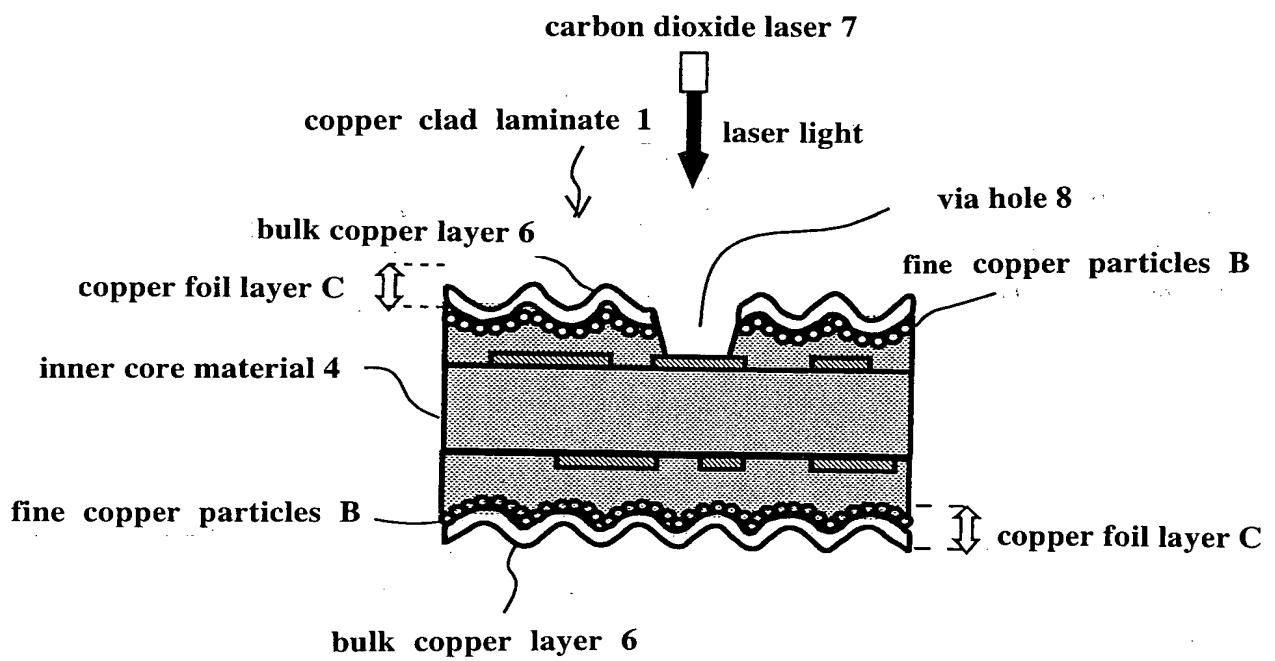
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# FIG. 6

(b) Peeling of Carrier Foil

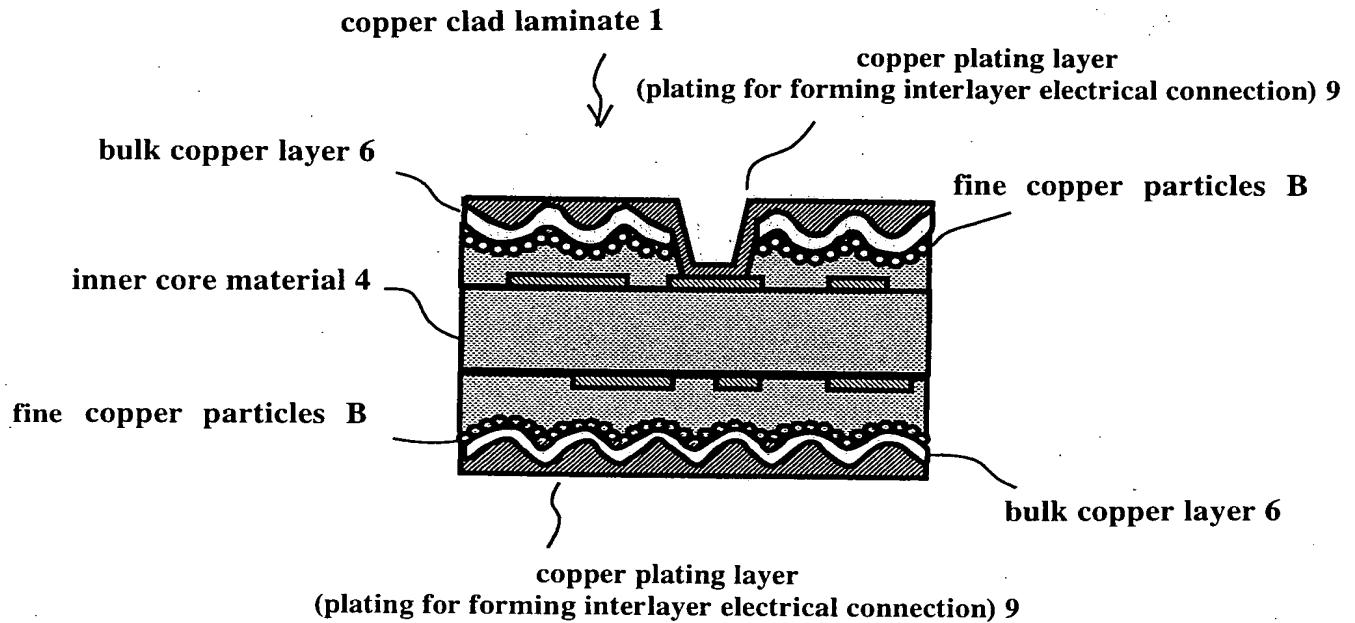


(c) Laser Treatment for Forming Holes



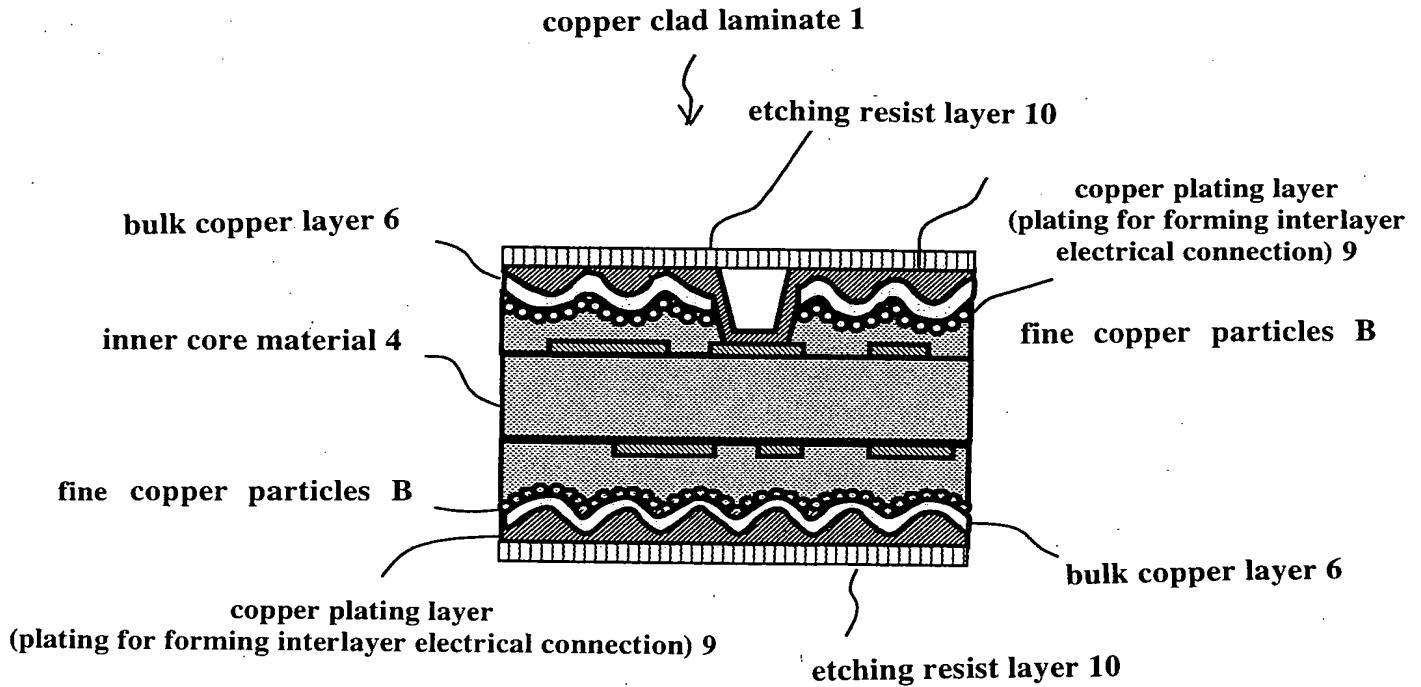
# FIG. 7

## (d) Copper Plating for Forming Interlayer Electrical Connection



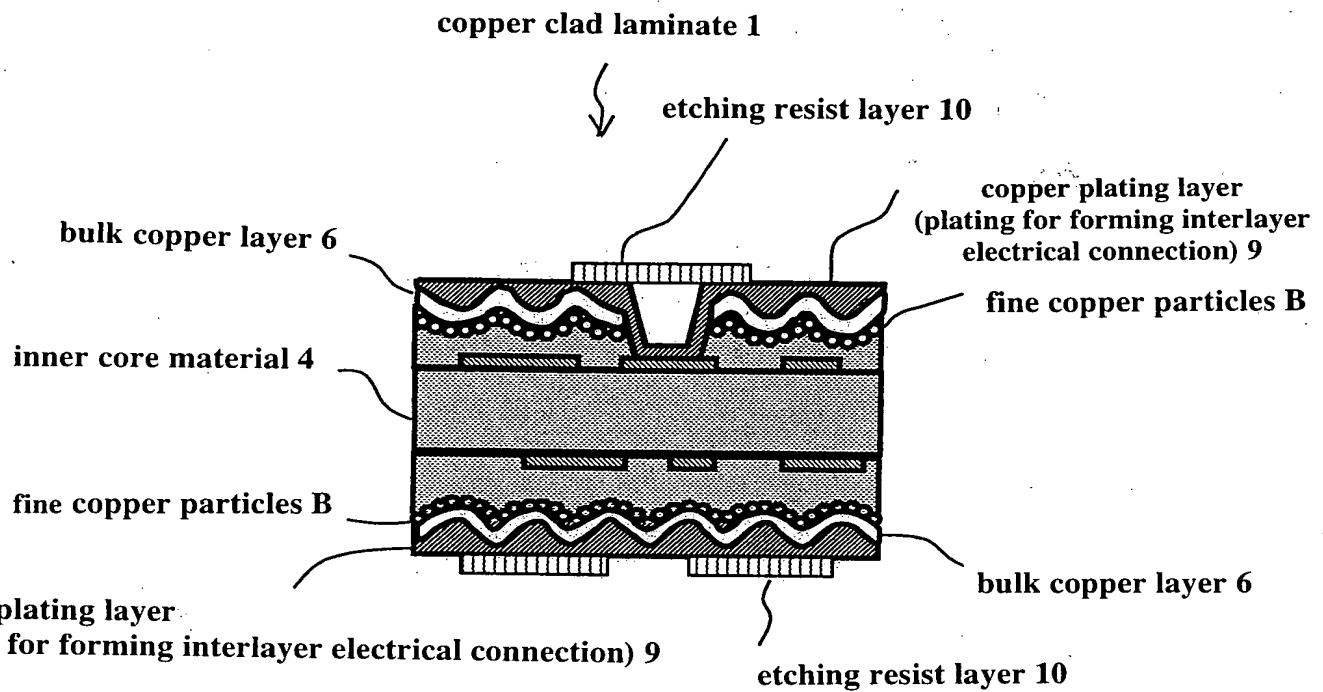
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## (e) Forming Etching Resist Layers

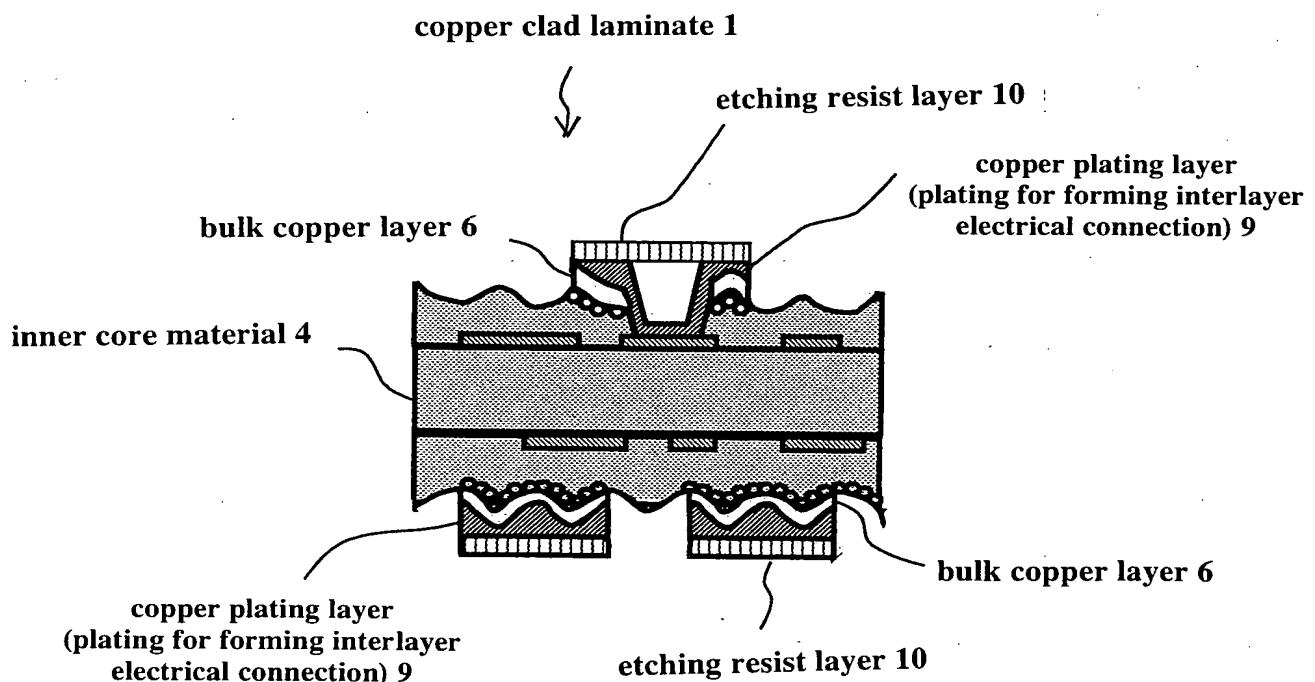


# FIG. 8

## (f) Exposing and Developing the Etching Resist Layers



## (g) Copper Etching



# **FIG. 9**

## **(h) Peering of Etching Resist Layers**

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